

# MA2C185 (MA185)

## Silicon epitaxial planar type

For high-voltage switching circuits, small power rectification

### ■ Features

- High reverse voltage
- Large output current  $I_O$
- Allowing to insert into a 5 mm pitch hole

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	200	V
Maximum peak reverse voltage	$V_{RM}$	250	V
Output current	$I_O$	200	mA
Repetitive peak forward current	$I_{FRM}$	625	mA
Non-repetitive peak forward surge current *	$I_{FSM}$	1	A
Power dissipation (Average)	$P_{D(AV)}$	400	mW
Junction temperature	$T_j$	175	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-65 to +175	$^\circ\text{C}$

Note) \*:  $t = 1 \text{ s}$

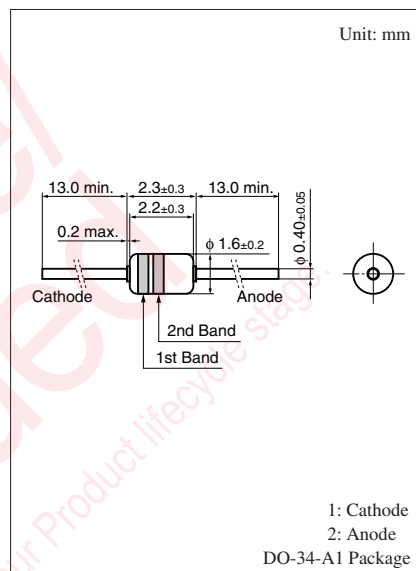
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 200 \text{ mA}$			1.2	V
Reverse voltage	$V_R$	$I_R = 100 \mu\text{A}$	250			V
Reverse current	$I_R$	$V_R = 200 \text{ V}$			200	nA

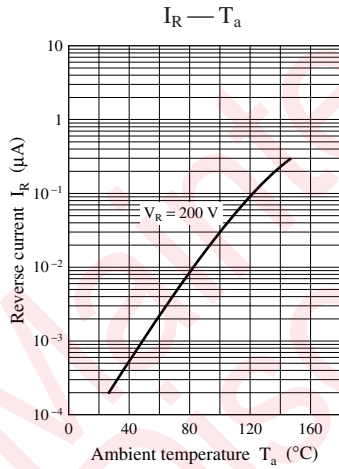
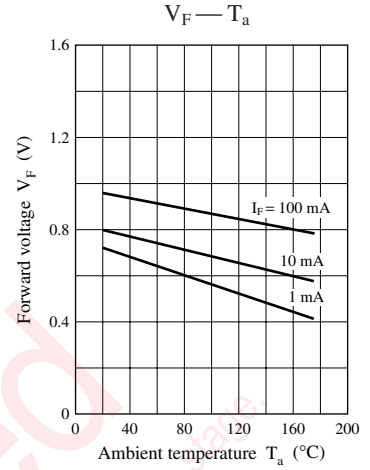
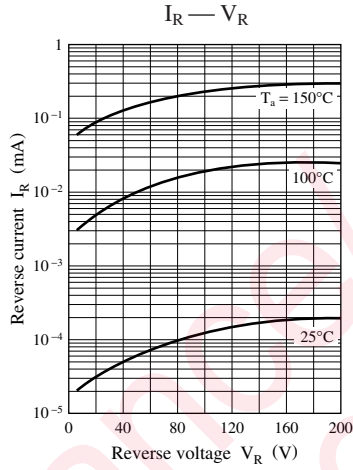
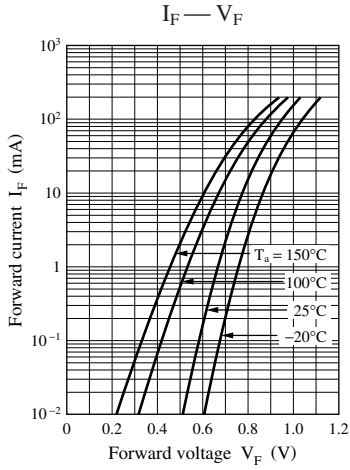
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.  
2. Absolute frequency of input and output is 3 MHz.

### ■ Cathode Indication

Type No.		
Color	1st Band	White
	2nd Band	Green



Note) The part number in the parenthesis shows conventional part number.



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